

RESEARCH OF AC-LGAD STRIP DETECTOR FOR 4D TRACKING

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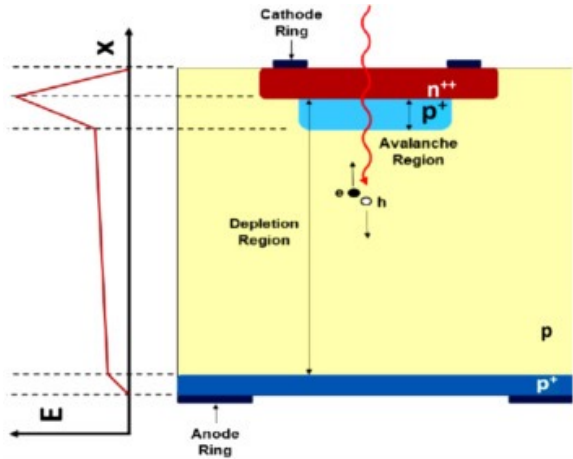
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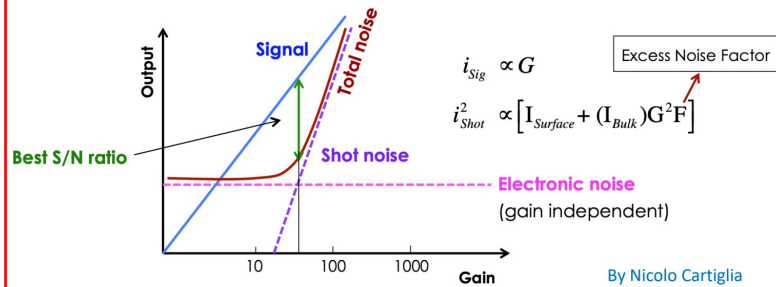
Institute of High Energy Physics, Chinese Academy of Sciences

LGAD and AC-LGAD

LGAD: Low-Gain Avalanche Diode



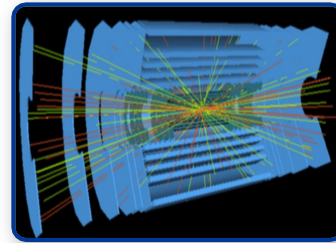
- High electric field in the gain layer
- Multiplication
- Good SNR due to low gain



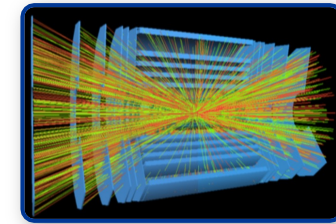
Noise increases faster than the signal
 → the ratio S/N becomes worse at higher gain

<https://doi.org/10.1201/9781003131946>

ATLAS @ LHC

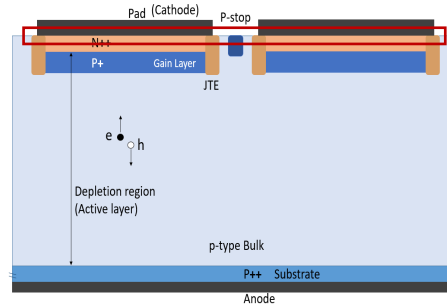


ATLAS @ HL-LHC

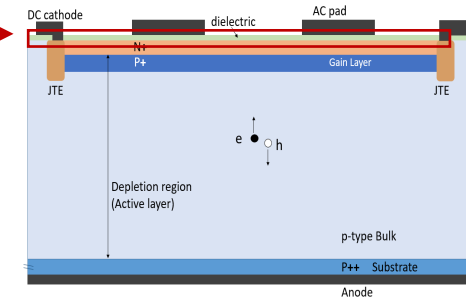


HGTD based on LGAD:

Proposed to address severe pile-up in HL-LHC phase



LGAD (Low-Gain Avalanche Diode)



AC-LGAD (AC-coupled LGAD)

Dielectric

- Metal pads are **connected** to n++ layer
- Time resolution ~ 30ps
- Position resolution: $\text{pixel size}/\sqrt{12}$
- Radiation hardness: $10^{15} \sim 10^{16} n_{eq}/cm^2$

- Metal AC-pads are **separated** from the n+ layer by a thin dielectric (Si_3N_4 , SiO_2)
- **No dead zone** (100% fill factor)
- Time resolution ~ 30ps
- Position resolution: $5 \sim 10 \mu m$
- Radiation hardness: $10^{15} \sim 10^{16} n_{eq}/cm^2$

Motivation

- LGAD based silicon sensors can provide precise timing information, while AC-LGAD as a new 4D detector, **can provide the position information at the same time.**

DRDT 3.2 - Develop solid state sensors with 4D-capabilities for tracking and calorimetry

Understanding the ultimate limit of precision timing in sensors, with and without internal multiplication, requires extensive research and developments to increase radiation tolerance and achieve 100% fill factors. New semiconductor and technology processes with faster signal development and low noise readout properties should also be investigated

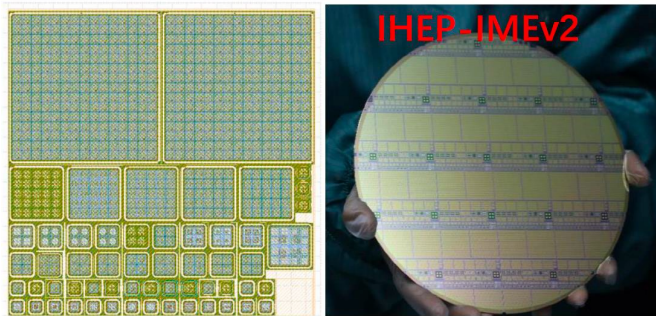
WG2 research goals <2027	
	Description
RG 2.1	Reduction of pixel cell size for 3D sensors
RG 2.2	3D sensors for timing ($< 55 \times 55 \mu\text{m}$, $< 50 \text{ ps}$)
RG 2.3	LGAD for 4D tracking $< 10 \mu\text{m}$, $< 30 \text{ ps}$, wafer 6" and 8"
RG 2.4	LGAD for ToF (Large area, $< 30 \mu\text{m}$, $< 30 \text{ ps}$)

- **RG 2.3: LGAD Sensors with very high fill factor, and an excellent spatial and temporal resolution.**
 - 2024-2025: LGAD test structures of different technologies (TI-LGAD, iLGAD, AC-LGAD/RSD, DJ-LGAD), matching existing read-out ASICs.
 - 2026-2028: Large LGAD sensors based on the best-performing technology.
 - 2025-2028: Investigation of radiation hardness of LGAD technology beyond $\sim 2.5 \cdot 10^{15} \text{ n}_{\text{eq}}/\text{cm}^2$.
- **RG 2.4: LGAD sensors for Time-of-Flight applications**
 - 2024-2026: Production of LGAD sensors with large size for Tracking/Time-of-Flight applications to demonstrate yield and doping homogeneity. Study of spatial and temporal resolutions as a function of the pixel size.
 - 2026-2028: LGAD structures with 4D capabilities produced with vendors capable of large-area productions to demonstrate the industrialization of the process.

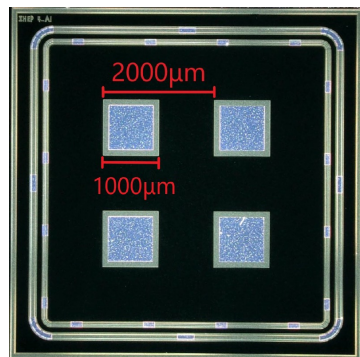
- The project has been proposed at 1st DRD3 meeting.

Develop LGAD based silicon sensors and detector modules for the outer tracker and time-of-flight layer in future colliders (CEPC, FCC-ee, ILC, CLIC, etc.)

AC-LGAD Research in IHEP



AC-LGAD R&Dv1:



Pixelated AC-LGAD

- With different pad-pitch size

1000-2000um

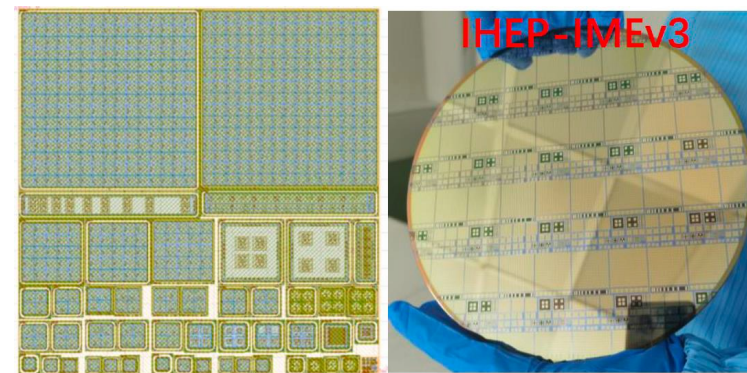
100-500um

100-200um

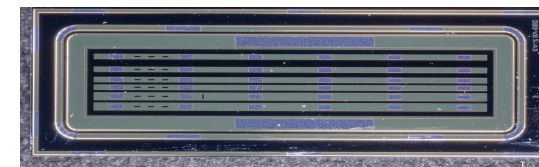
50-100um

- wafers: with different n+ dose: 10P to 0.2P

Process parameters have been studied.



AC-LGAD R&Dv2:



Pixelated and strip AC-LGAD

- With different pad-pitch size

1000-2000um pixel

100-250um strip

100-150um strip

50-100um strip

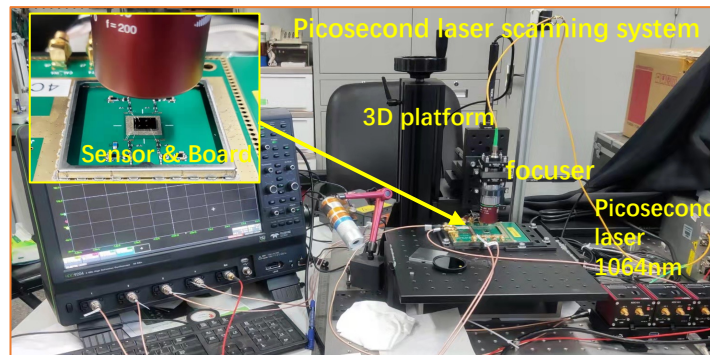
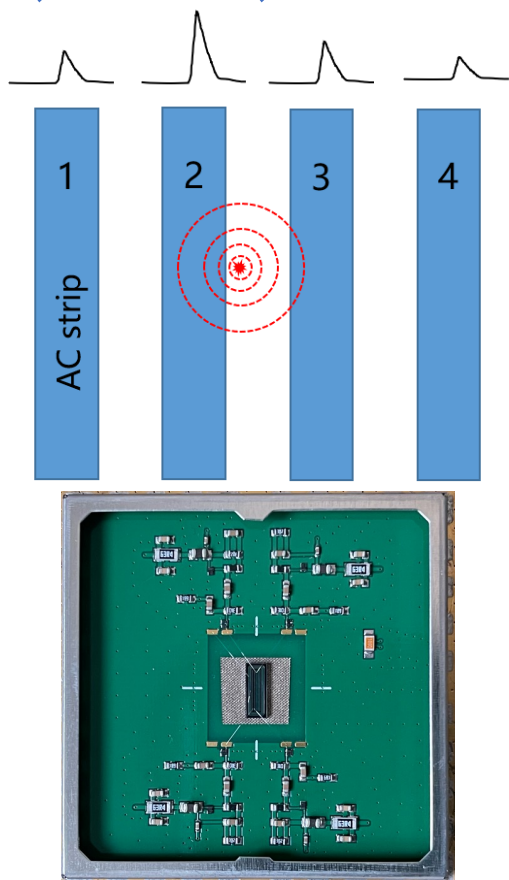
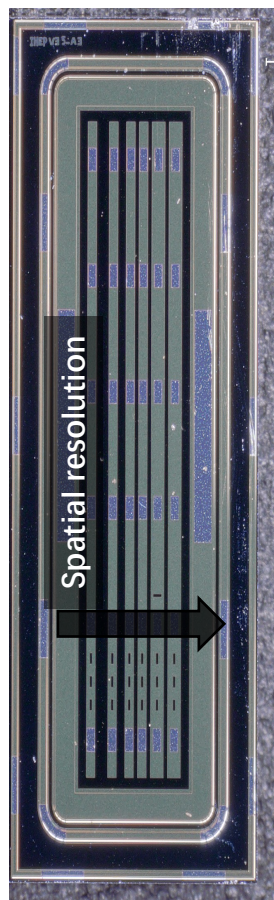
- wafers: with different n+ dose:0.2P to0.01P

First trial in AC-LGAD Strip

AC-LGAD Strip

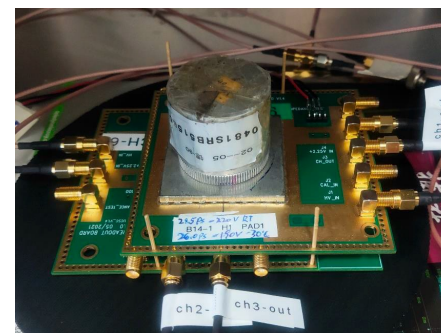
AC-LGAD Strip:

- Position information: 2 layer
- Strip length 5.6mm, width 100 μ m
- Different Pitch size:
 - 150 μ m、200 μ m、250 μ m



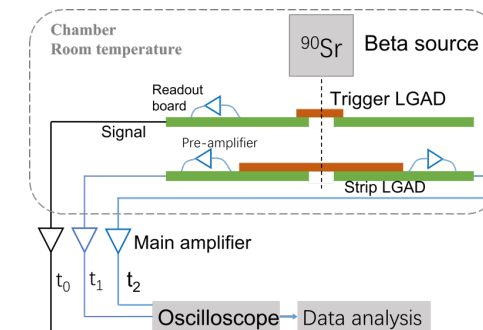
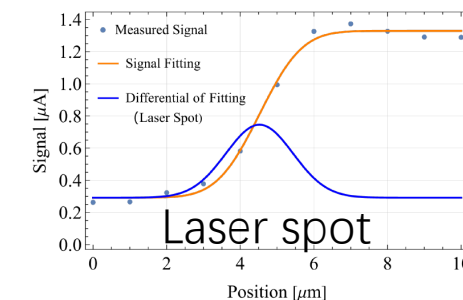
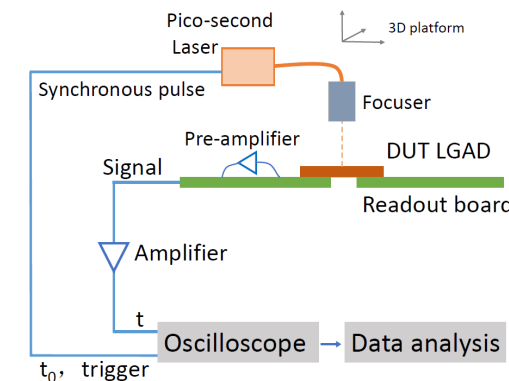
Picosecond laser scanning system

- Displacement accuracy 1 μ m
- Automated scanning
- Picosecond laser 1064nm
- Spot size 2~5 μ m

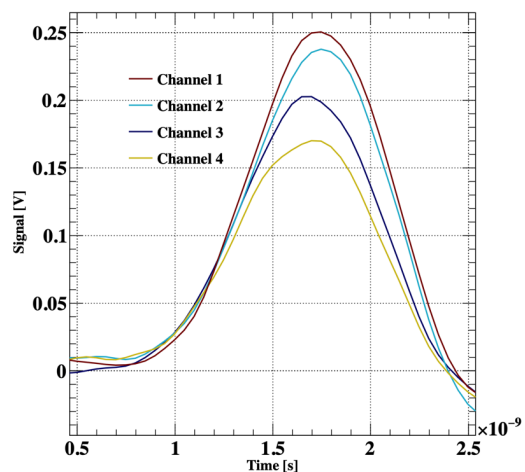


Beta source test system

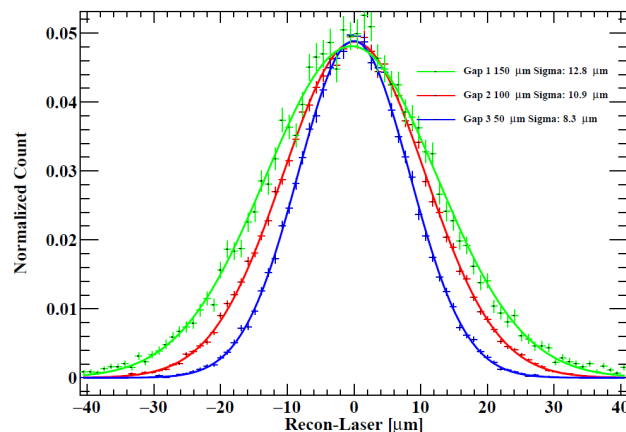
- Strontium-90 2MeV MIP
- With trigger LGAD



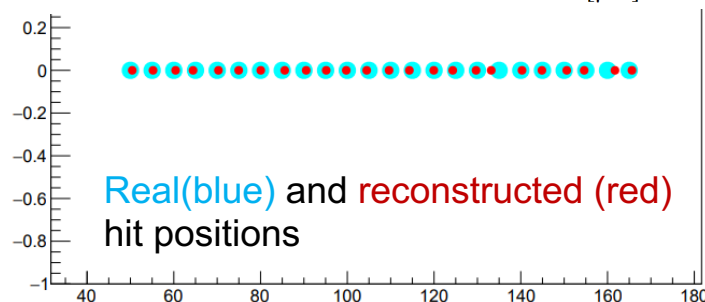
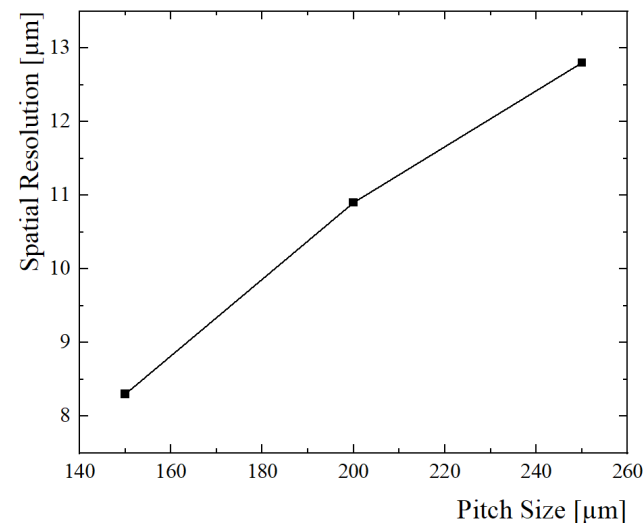
Signal properties and spatial resolution



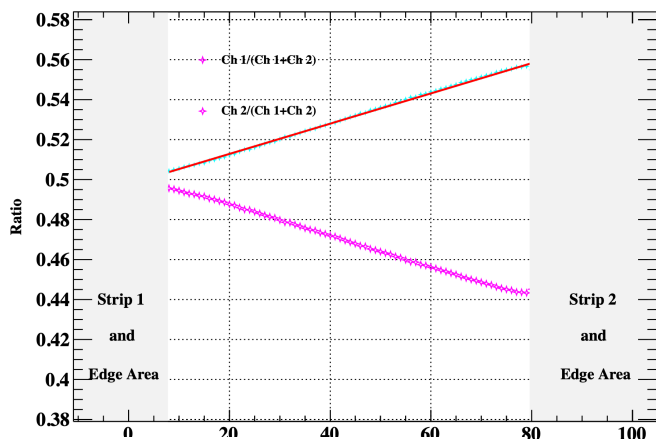
Waveforms on 4 strips of a laser hit



Distribution of difference between real and reconstructed laser hit position
Best spatial resolution: **8.3 μm**



- Good consistency between the reconstruction position and the laser position
- The smaller the pitch size, the better the spatial resolution
- The rise in spatial resolution values is **slower** than linear with increasing Pitch size

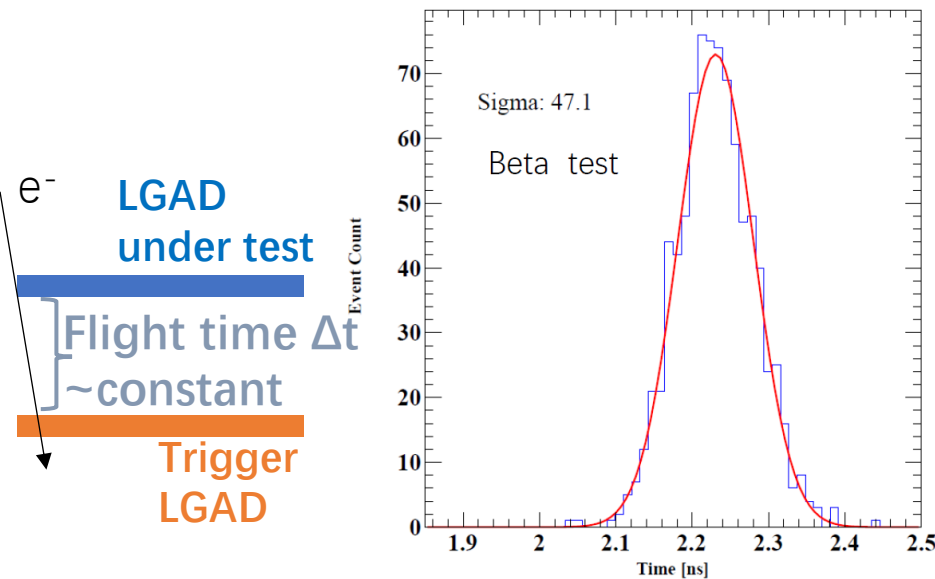


$$R = \frac{Amp_2}{Amp_1 + Amp_2}$$

Position reconstruction:

- Based on resistor networks, the fraction of the signal (R) changes linearly with laser position between gaps.
- Distortion observed at approach to edge region
- Better than **8.3 μm** with 150 μm pitch, and approx. **12 μm** with 250 μm pitch

Time resolution of AC-LGAD Strip

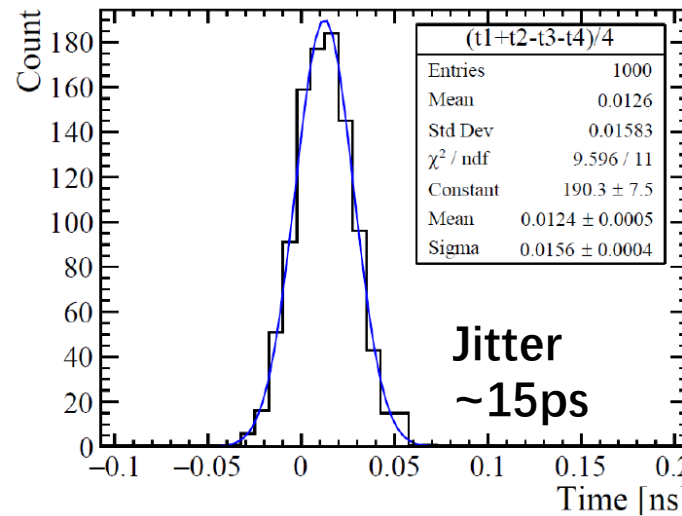


Distribution of Δt

Sigma $\Delta t = 47.1$ ps

Time resolution: best **37.5 ps**

Jitter ~ 15 ps

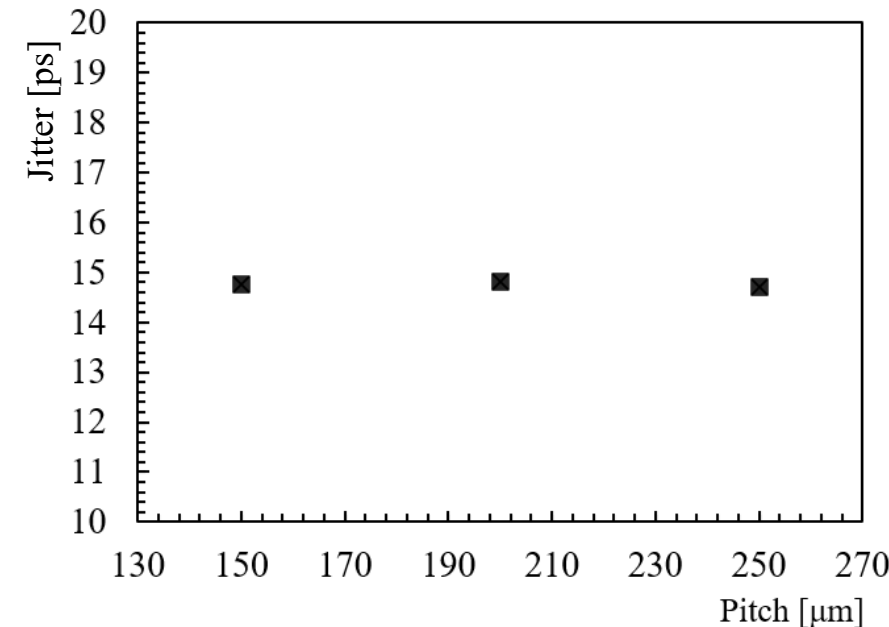


Time Resolution

$$\Delta T = T_{trigger} - \frac{\sum_i a_i^2 T_i}{\sum_i a_i^2}$$

Time resolution of trigger

Weighted time resolution of AC-LGAD

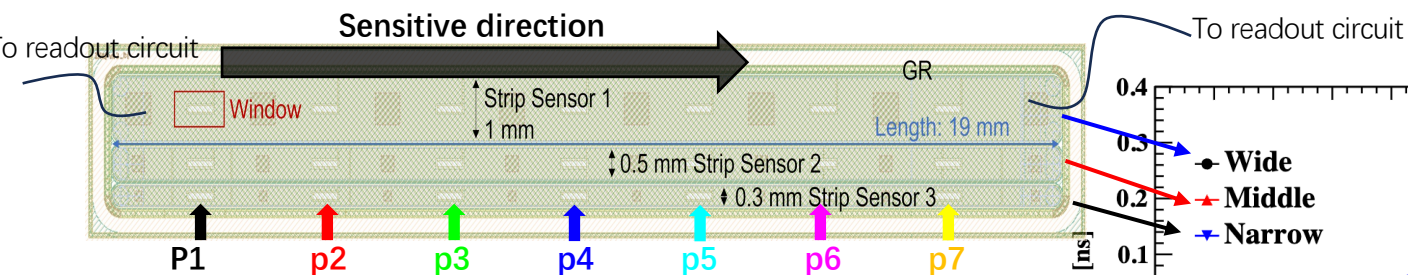


Jitter Vs. pitch size -laser test

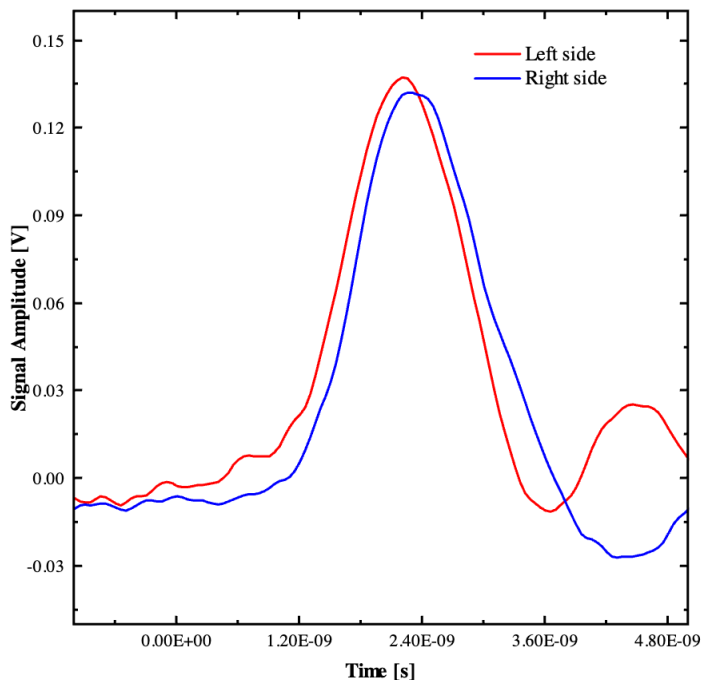
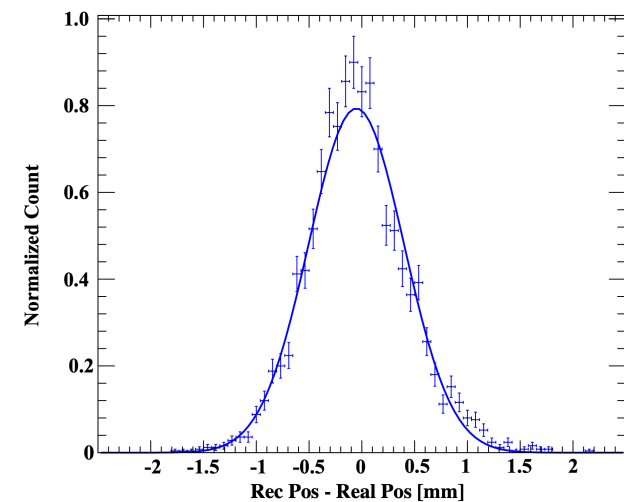
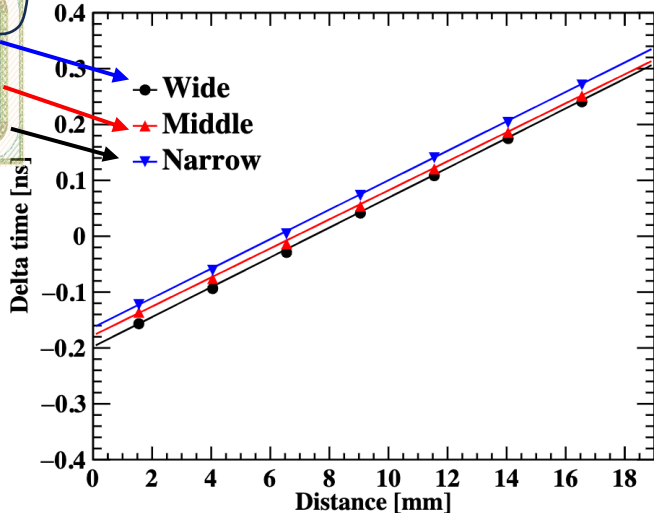
- ~ 37 ps timing resolution AC-LGAD, via Beta source test.
- No significant change in timing resolution was observed among pixel, strip AC-LGADs
- Jitter, ~ 15 ps, not change with pitch

$$\sigma_t^2 = \sigma_{TimeWalk}^2 + \sigma_{Landau}^2 + \sigma_{Jitter}^2$$

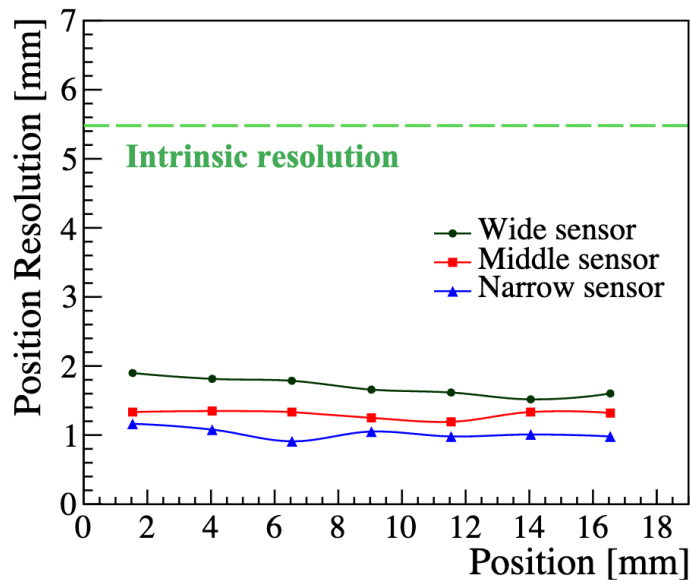
LGAD-Strip Spatial resolution



Double-end Readout of LGAD strip
 Length: 20mm with 0.3, 0.5 and 1 mm width
LGAD-Strip, Not AC-LGAD



Waveform Variation at two ends



Position reconstruction:

- Based on time-lag between two ends
- Good linearity

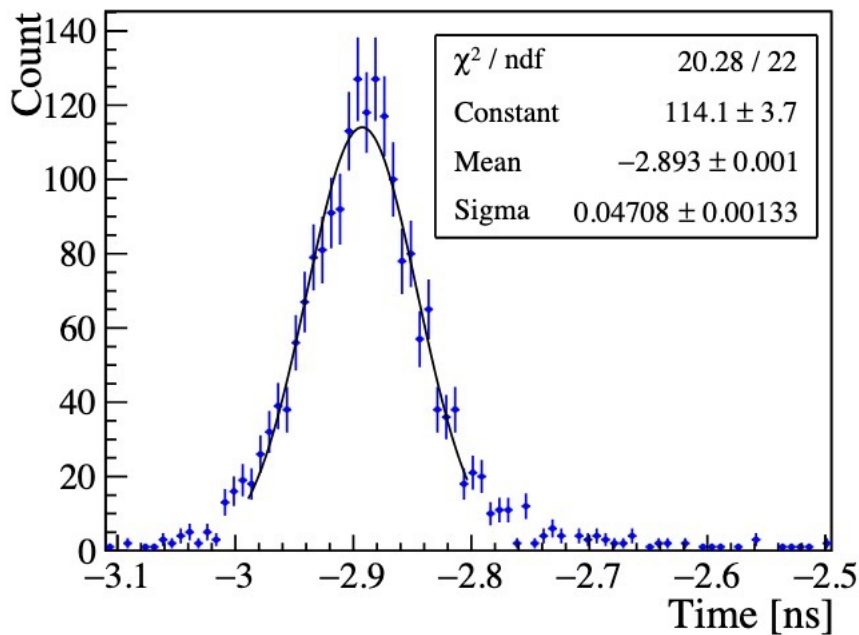
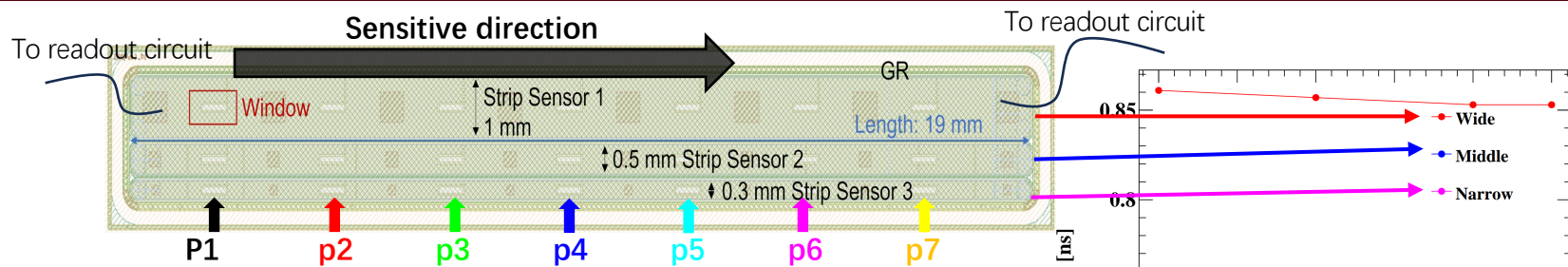
Position resolution along Z

0.9 mm

Intrinsic: **5.5 mm**

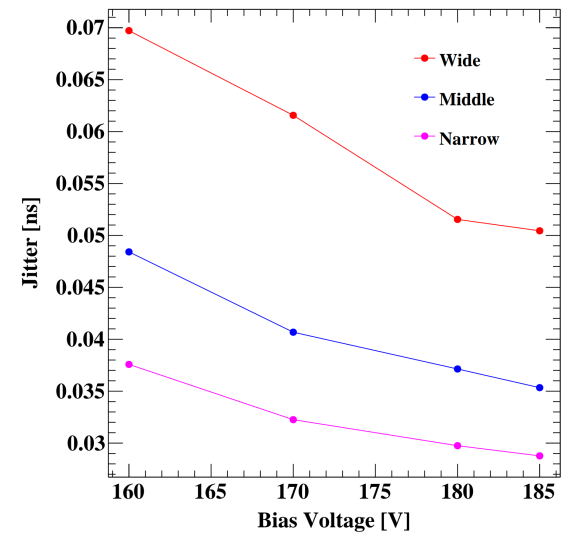
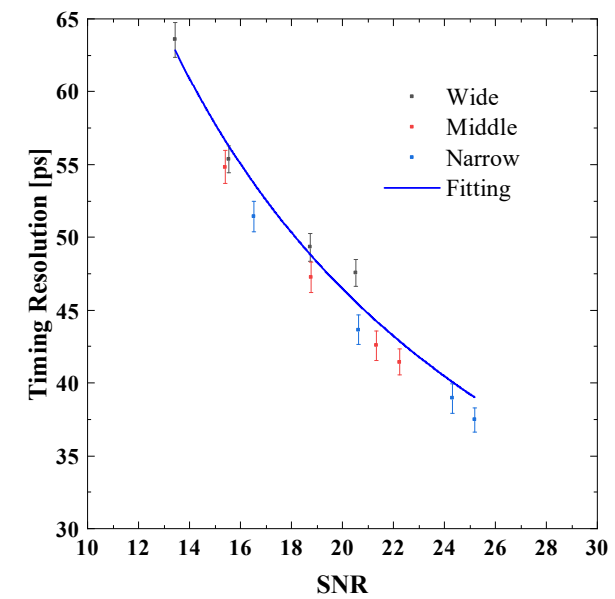
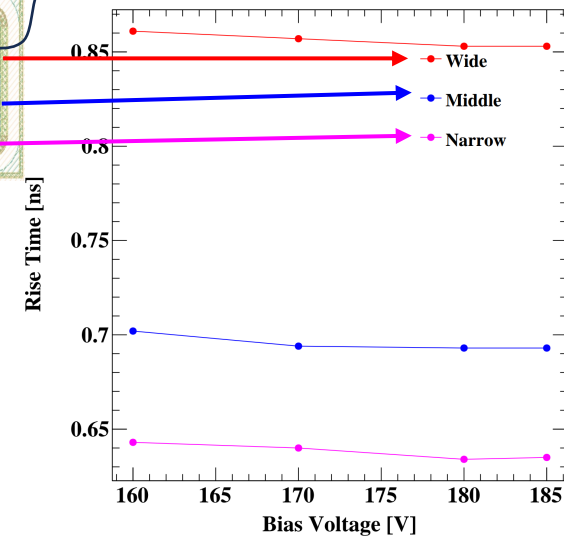
Total length: 19mm

LGAD-Strip Time Resolution



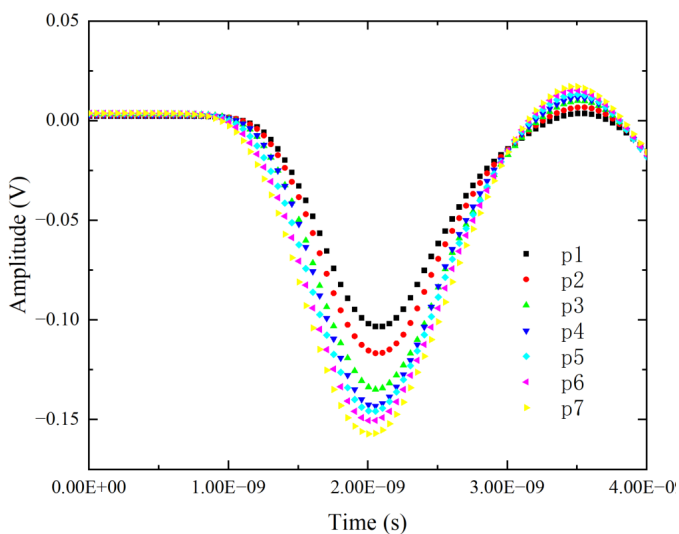
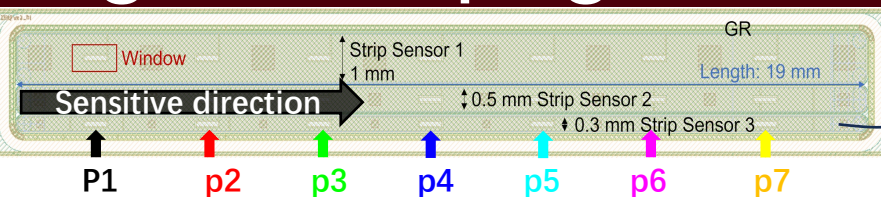
Time resolution of **LGAD-strip** :
best 37 ps —double end readout

Similar method with AC-LGAD strip



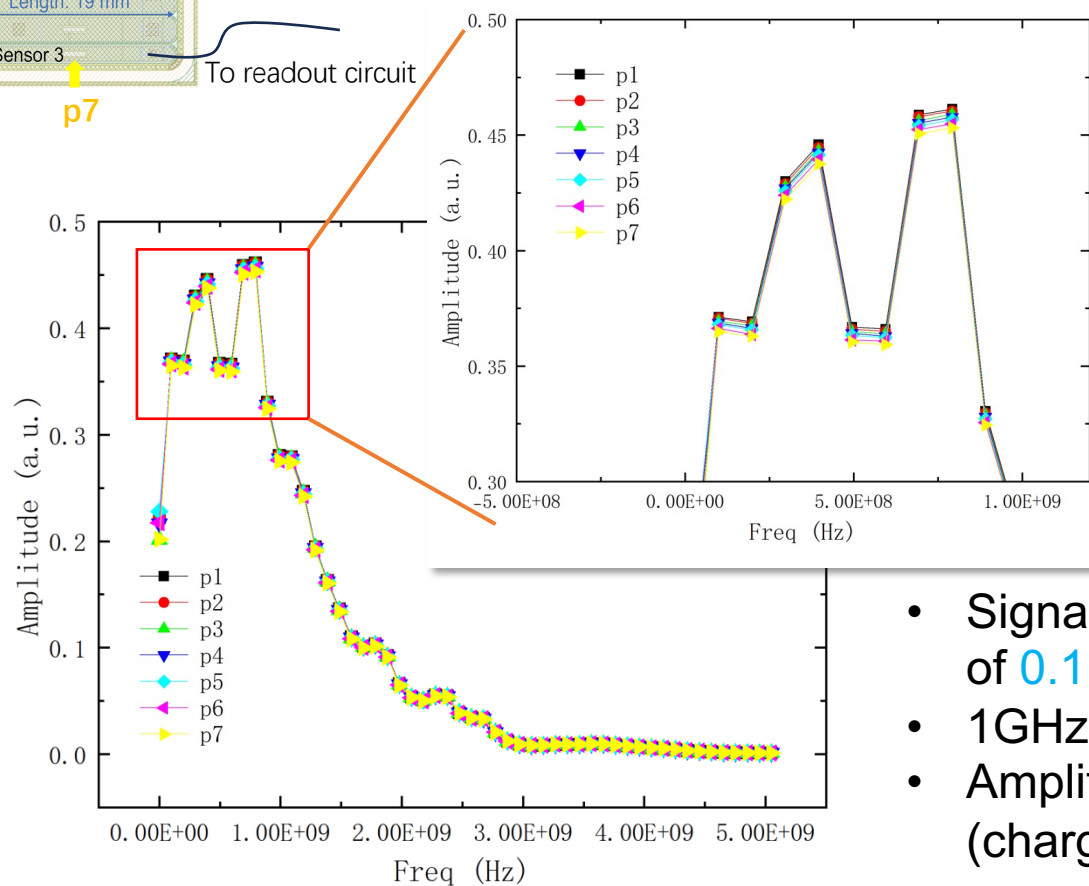
- Jitter decreases with decrease of sensor area
- Dominant of time resolution
- Rise time not change with bias voltage
- $Time\ resolution \approx \frac{Risetime}{SNR}$
- This holds for 2cm scale LGAD

Signal Propagation Properties—Transmission Line?



Waveform at different hit positions
From P1 to P7

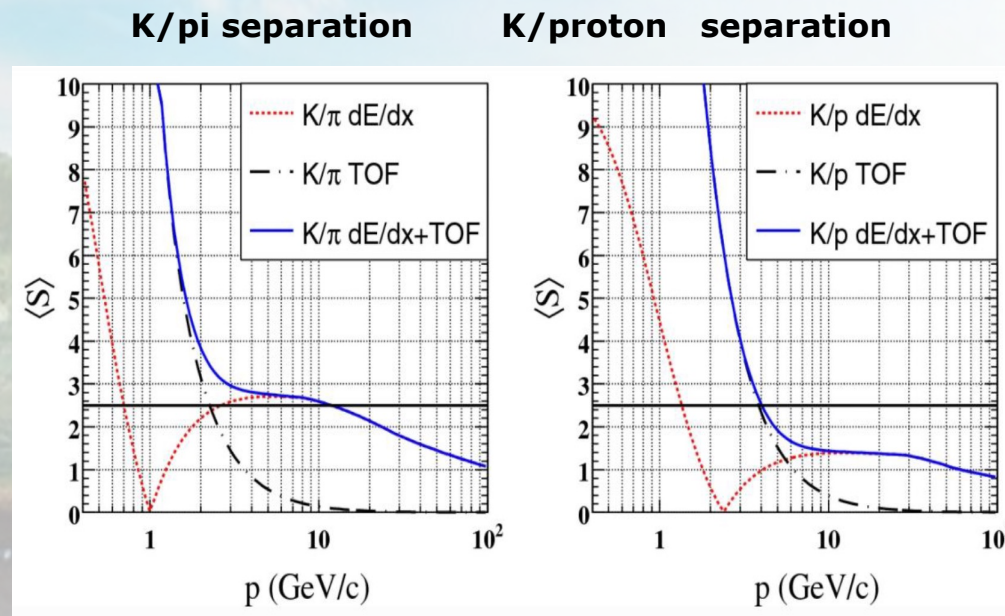
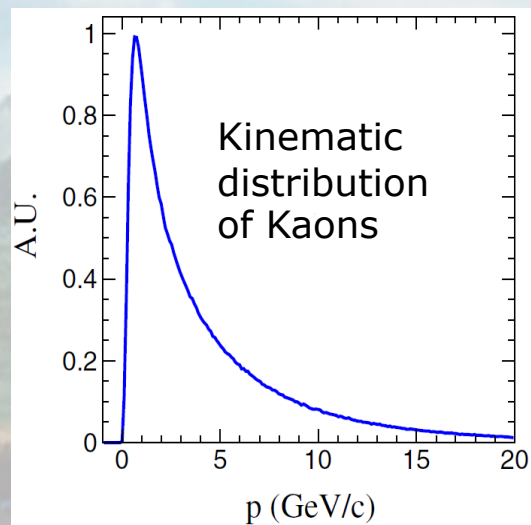
- DC-LGAD with low n+ resistance
- For AC-LGAD and high resistance n+ device, things may change, still need to demonstrate.



Spectrogram of hit position P1-P7

- transmission line effect
 - Skin effect: Resistance variation with frequency, especially for high frequency signals
 - Dielectric Loss: Lost due to dielectric materials
- **Total loss is related to frequency**

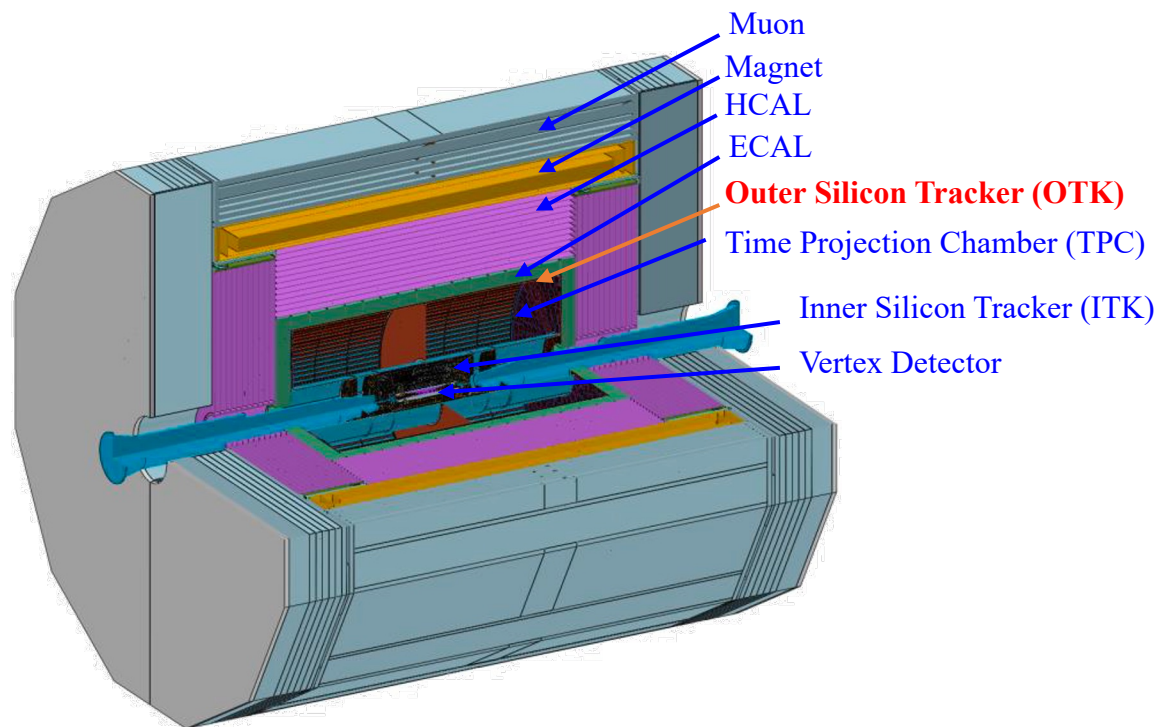
- Signal frequencies mainly in the range of 0.1 to 1.5GHz
- 1GHz dominant
- Amplitudes and areas of waveform (charge) of one end differ, but summation of two ends maintain the same
- In the spectrogram, no significant difference shows in the amplitude of the frequencies among P1-P7



Circular Electron Positron Collider (CEPC)—A Higgs factory to run at $\sqrt{S} \sim 240$ GeV.

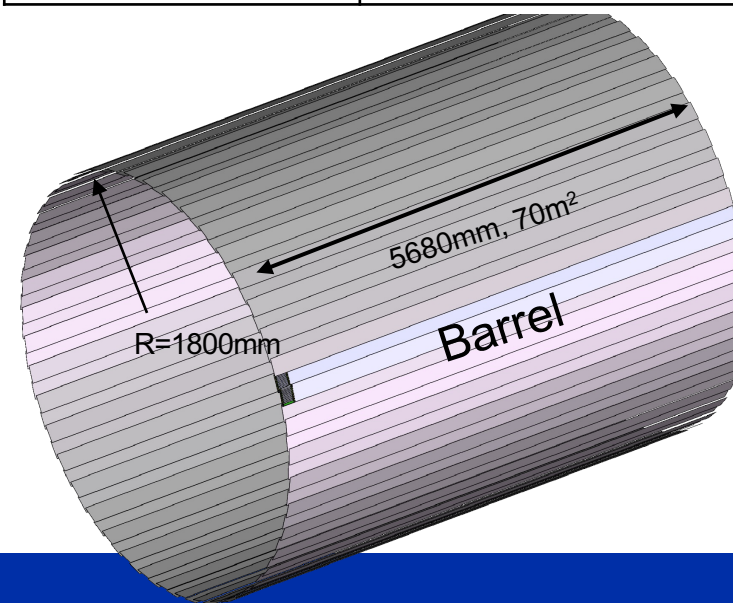
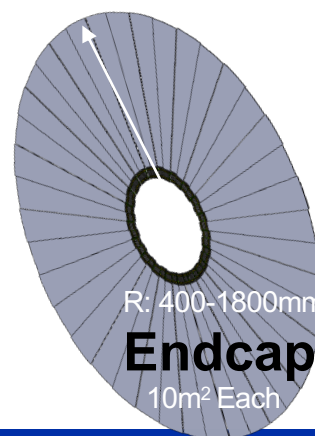
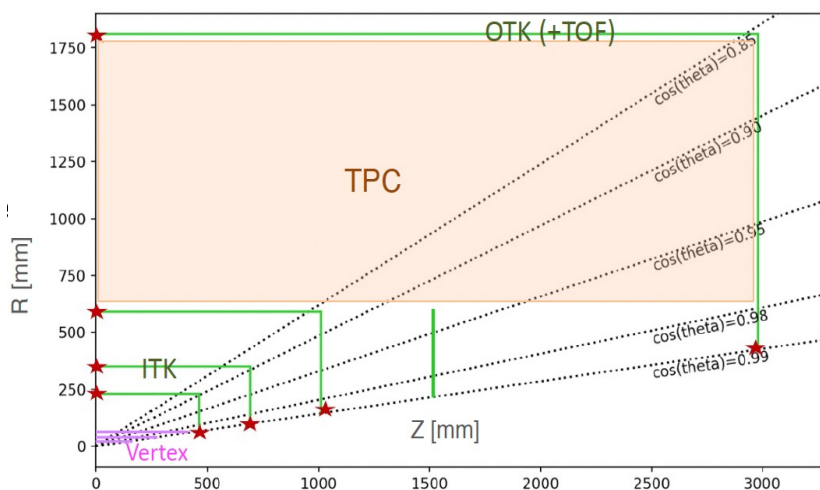
To produce above
1M Higgs at ZH mode
Tera Z at Z pole mode

- Multi-targets—Higgs, electroweak, flavor physics.....
- **LGAD based OTK(+ToF)** will be placed between TPC and ECAL
- Time detector is complementary to gaseous detector
- Improve particle separation ability:
--0-4GeV for K/Pi separation, 0-8 GeV for K/p separation



Design target of CEPC ToF Barrel

Area	~ 70 m ²
Radius	1.8m
Length	5.8m
Strip Length	20 mm (to be determined)
Strip Pitch	100-500 μm (to be determined)
Channel number	~ 10 ⁷ channels
MIP Time resolution	~50 ps
Spatial resolution	~ 10 μm (R-Φ)



New Trials

- Long strip AC-LGAD simulation ongoing
- Optimized structure design of AC-LGAD:

- Pixelated AC-LGAD: different pixel size
- Strip AC-LGAD:
 - Different strip length\different pad-pitch size(1cm, 2cm, 4cm long; pitch: 50um to 500um...)
 - Design for endcap region: Sectoral AC-LGAD strip sensors
 - Strip AC-LGAD with different p-stop isolation structure

- Strip DC-LGAD:

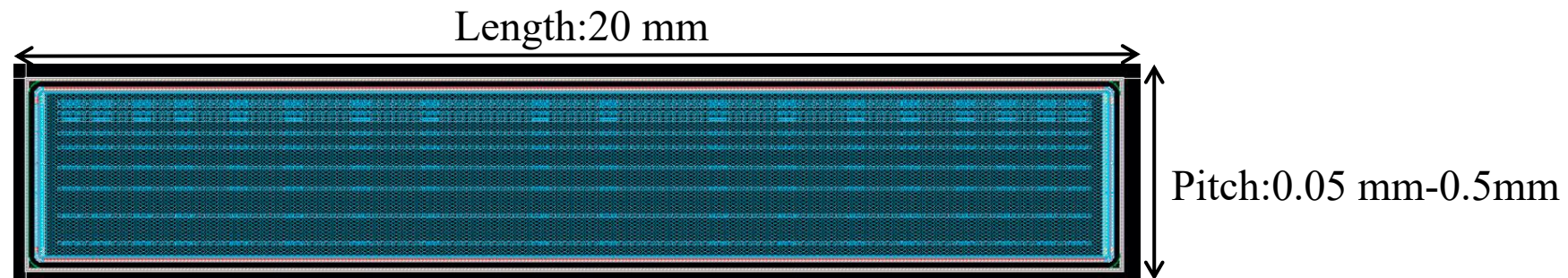
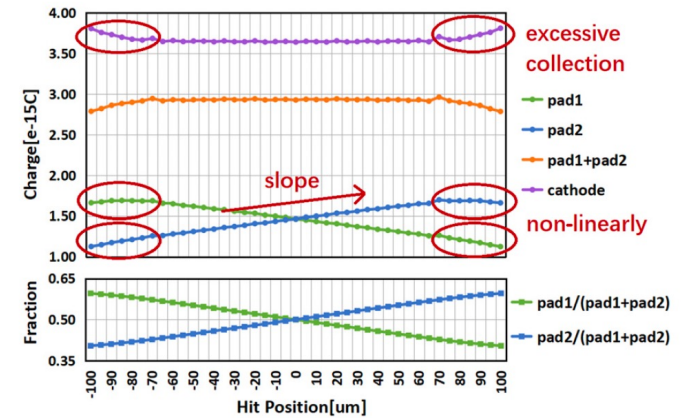
Different strip length\different pad-pitch size(1cm, 2cm, 4cm long; pitch: 50um to 500um...)

...

- Process parameters design of AC-LGAD:

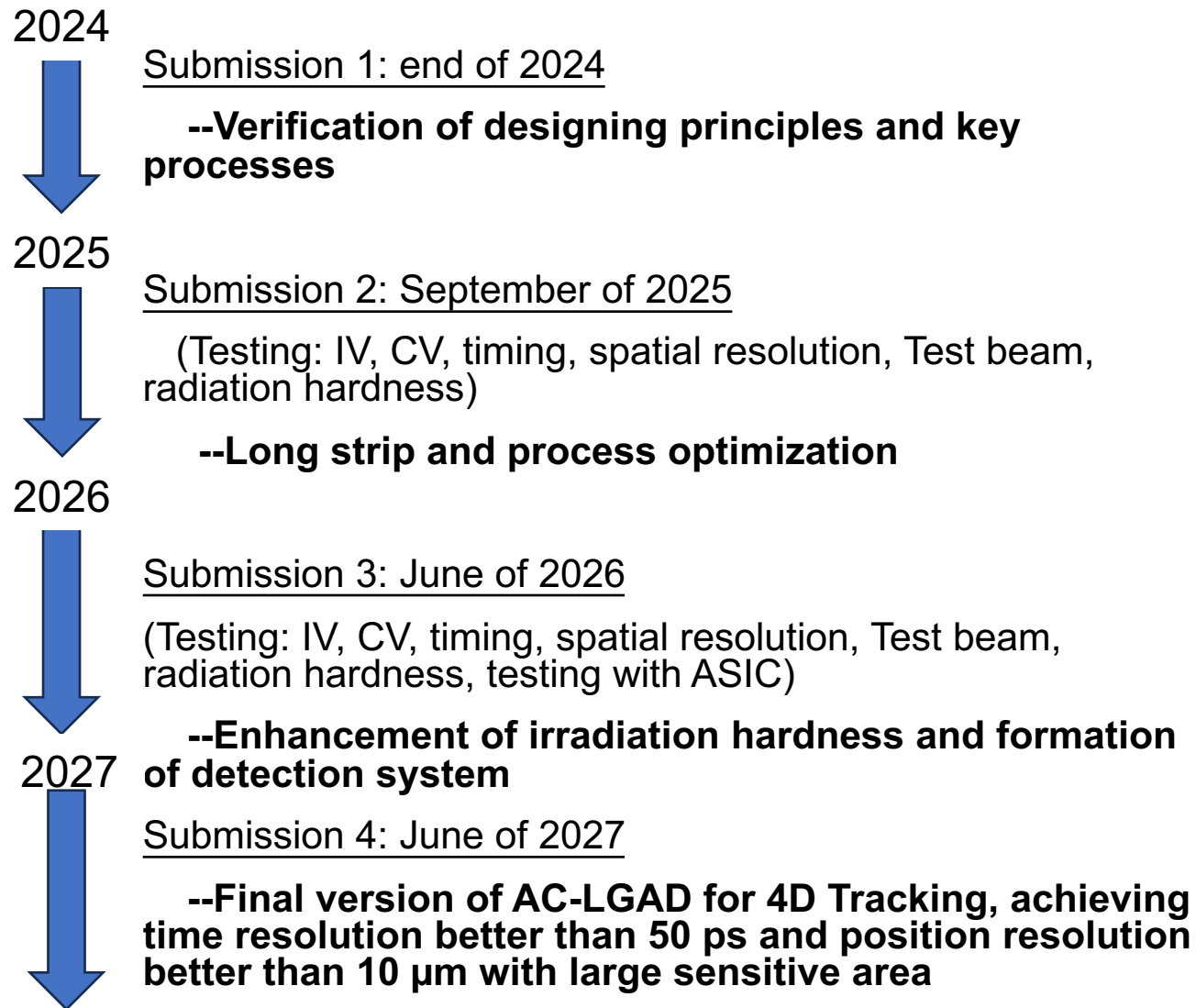
- AC Coupling capacitor(insulating material)
- N+ layer doping dose

...



To do list.....

➤(Ideal) Timetable of AC-LGAD:



• Topic:

- 1、 AC-LGAD simulation, design and fabrication
- 2、 AC-LGAD testing: IV, CV, timing, spatial resolution, gain, etc
- 3、 AC-LGAD Test beam testing
- 4、 Radiation performance (TID, neutron, proton)
- 5、 Position reconstruction methods
- 6、 Design optimization for electron collider
- 7、 Sensor with ASIC(TDC board) testing on system level
- 8、 Application of AC-LGAD as 4D detector
-

Collaborations

Collaboration board

CB Chair: G. Pellegrini (CNM)
Deputy: R. Arcidiacono (INFN-TO)

Steering committee:
DRD3 management + CB
Chair + WG conveners

DRD3 management

G. Kramberger (JSI) - SP
M. Moll (CERN)-DSP
I. Gregor (DESY)-DSP
S. Seidel (UNM)-DSP

R&D activities

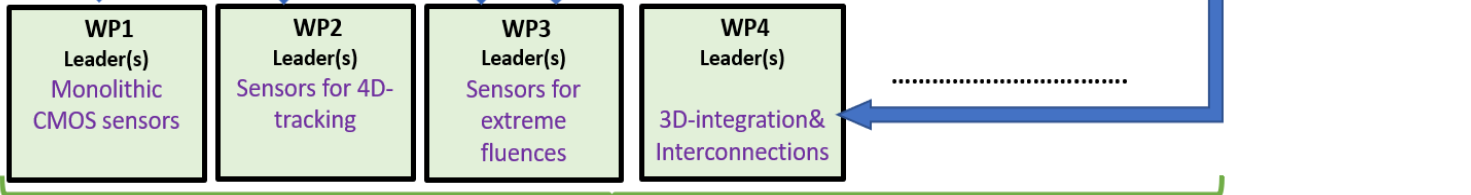
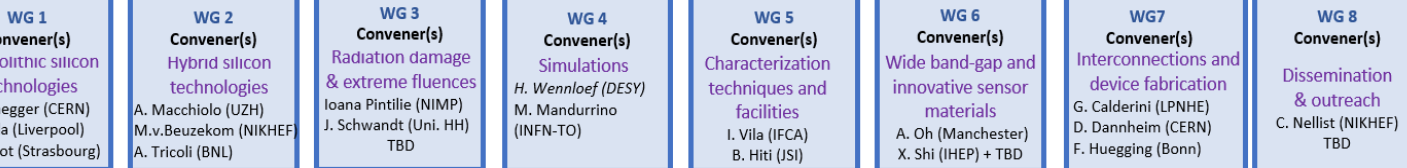
DRD3 bodies

Secretariat/administration

Resource coordinator /Project
office (D. Muensterman, HRM/Lancaster)

Cross-DRD coordination
CPAD coordination

Speakers committee
(U. Parzefall - Freiburg)



Strategic/Targeted R&D projects

Detector R&D (DRD)



Alessandro Tricoli

Cross WG activities

- WG3- Sensor irradiation performance study
- WG4 - Simulation of process and structure parameters for fabrication of AC-LGAD
- WG5 – Beam test to check AC-LGAD timing and spatial performance
- WG6- sensor and ASIC connected methods

Cross DRD collaborations

- DRD4, Photo-Det./PID, AC-LGAD's application as photo detector or X-ray detector
- DRD7, Electronics, AC-LGAD readout ASIC, providing TOA and TOT information, ASIC and sensor testing board

Summery and Invitation

Participants for now

-  ➤ Institute of high energy physics, Chinese Academy of Sciences(IHEP)
-  ➤ Institute of Microelectronics, Chinese Academy of Sciences(IME)
-  ➤ Jozef Stefan Institute, Ljubljana (JSI)
-  ➤ University of Montenegro (UCG)
Univerzitet Crne Gore
-  ➤ Shanghai Jiao Tong University(SJTU)
-  ➤ Shandong University (SDU)
-  ➤ Nankai University (NKU)
-  ➤ Zhengzhou University (ZZU)

- AC-LGAD has the potential to fulfill the requirements of DRD-3 4D tracker in terms of spatial and time resolution, sensitive area fill factor, etc.
- R&D of AC-LGAD has yielded promising results but still has a long way to go.....

You Are Warmly Invited to Join Us

Contact person:

Prof. Mei Zhao (IHEP-CAS), zhaomei@ihep.ac.cn

Project plan: <https://cds.cern.ch/record/2918306>

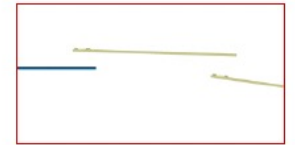
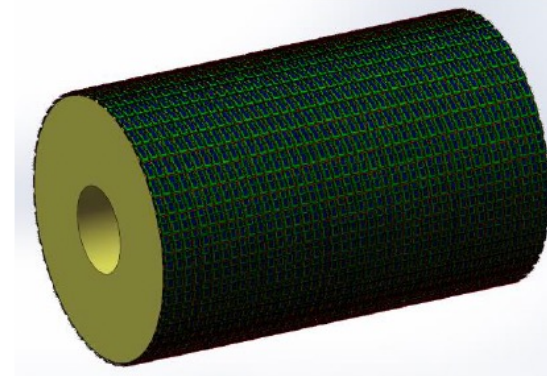
--DRD3-Working Group2 *Hybrid Silicon Technologies*
--DRD3-Working Package2 *Sensors for 4D Tracking*

Back up

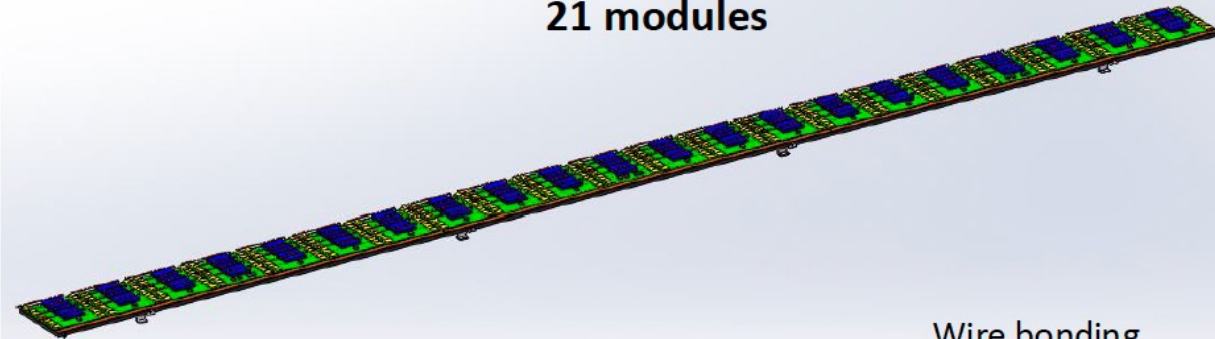
Design of the OTK with the strip AC-LGAD: Barrel

- one layer: 70 m², 3780 modules
 - R= 1800 mm ,H ~ 5800mm
 - overlap to decrease the dead area
 - 90 staves
 - 42 modules/stave

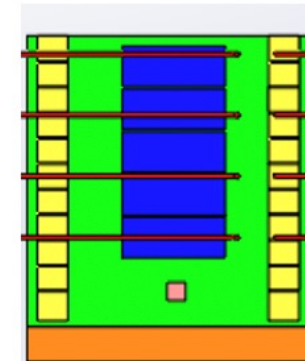
One layer ToF+OTK
R= 1800 mm , H~5800mm
90 staves



Long half stave
2900 mm x 160 mm
21 modules

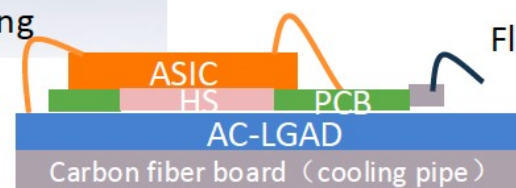


Module
137.8 mm x 160mm
22 ASICs



Wire bonding

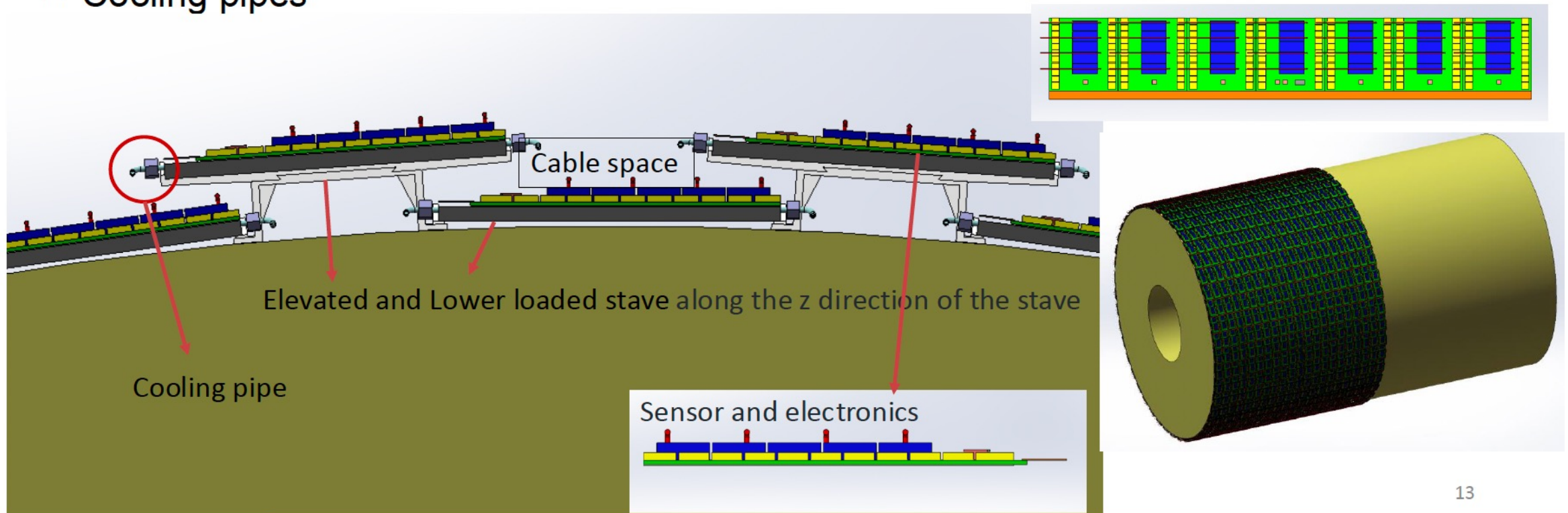
Flex cable



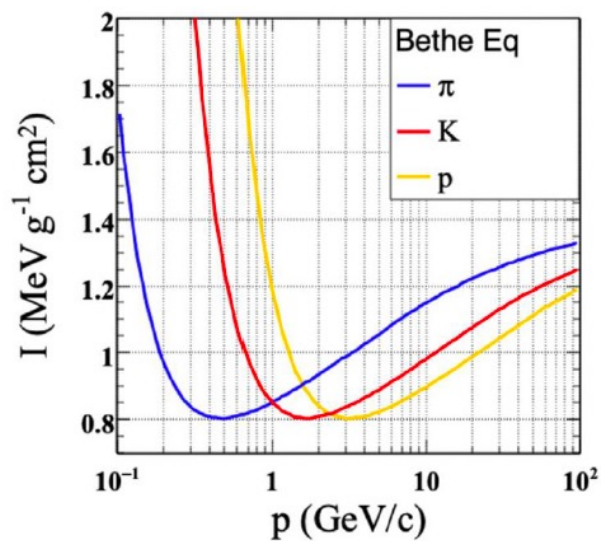
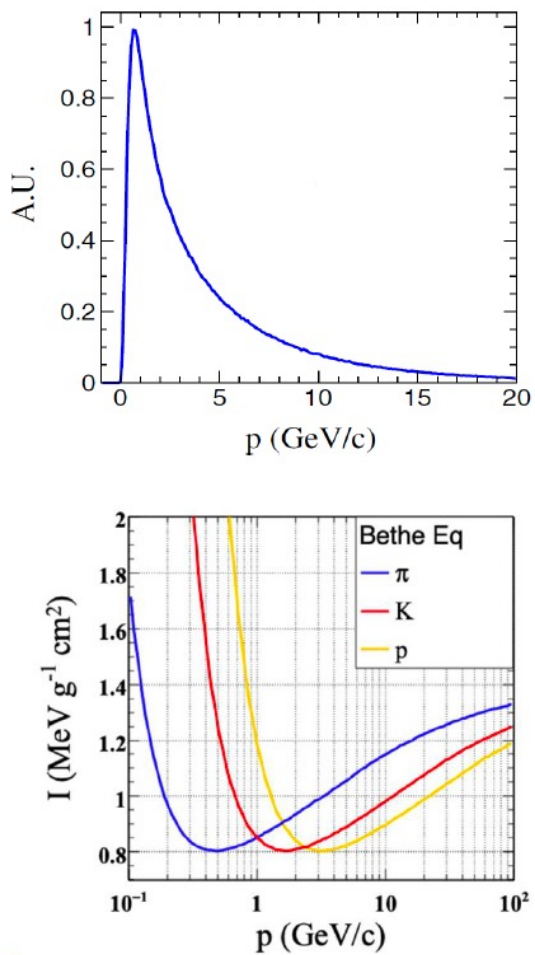
Heat sink(HS): Al;

Mechanical Design for LGAD ToF & OTK

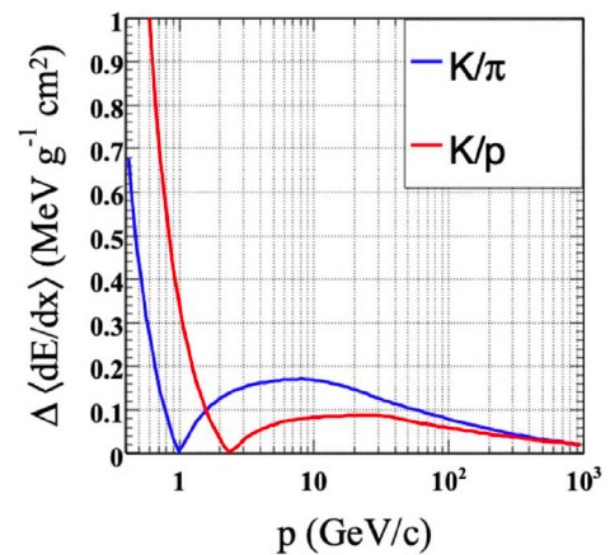
- Overlap staves for the barrel with detailed electronics design, cooling and installation
 - Special support design to allow precise alignment of the AC-LGAD sensors
 - Extra space for cables
 - Cooling pipes



■ TPC



(a)



(b)

Fig. 4. The distribution of I as a function of momentum for $K^\pm/\pi^\pm/\bar{p}^-$ (a) and the absolute difference of I for K^\pm/π^\pm and K^\pm/\bar{p}^- (b).